

POWER RECTIFIER DIODE

1N5550D3A / 1N5550D3B

- $V_{BR} = 220V$, $I_F = 5A$, Standard Reverse Recovery Rectifier Diode
- Light Weight Hermetic Ceramic Surface Mount Package
Designed as a Drop In Replacement for "D-5B" / "E-MELF"
Package†
- Switching Power Supply Applications
- Space Level and High-Reliability Screening Options Available



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise stated)

| | | |
|-------------|--|---------------|
| V_{BR} | Breakdown Voltage | 220V |
| V_{RWM} | Working Peak Reverse Voltage | 200V |
| I_O | Average Rectified Output Current, $T_{SP} = 130^\circ C$ | 5A |
| $I_O^{(1)}$ | Average Rectified Output Current, $T_A = 55^\circ C$ | 3A |
| I_{FSM} | Surge Current, $t_p = 8.3ms^{(2)}$ | 100A |
| T_J | Junction Temperature Range | -65 to +175°C |
| T_{stg} | Storage Temperature Range | -65 to +175°C |

THERMAL PROPERTIES

| Symbols | Parameters | Max. | Units |
|----------------------------|---|------|--------------|
| $R_{\theta JSP(IN)}$ | Thermal Resistance, Junction To Solder Pads $T_{SP} = 25^\circ C$ | 17 | $^\circ C/W$ |
| $R_{\theta JA(PCB)^{(3)}}$ | Thermal Resistance, Junction To Ambient, On PCB | 50 | $^\circ C/W$ |
| $R_{\theta JA(PCB)^{(4)}}$ | Thermal Resistance, Junction To Ambient, On PCB | 117 | $^\circ C/W$ |

Notes

- (1) I_{O1} is rated at 3.0A @ $T_A = 55^\circ C$ for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where $T_{J(Max)}$ does not exceed 175°C; This equates to $R_{\theta JA(PCB)} \leq 52^\circ C/W$. De-rate linearly 25mA/°C >55°C.
- (2) $T_A = 25^\circ C$ @ $I_O=3.0A$ and V_{RWM} for ten 8.3mS surges at 1 minute intervals.
- (3) PCB = FR4, 0.0625 Inch (1.59mm) thick, single layer, 1.0-Oz Cu, Pad Size, (1.0" x 1.0"), (645mm x 645mm), horizontal in still air.
- (4) PCB = FR4, 0.0625 Inch (1.59mm) thick, single layer, 1.0-Oz Cu, Pad Size, (0.070" x 0.155") \pm , (1.78mm x 3.94mm) \pm , horizontal in still air.
 I_{O1} is rated at 1.5A @ $T_A = 55^\circ C$ for PC boards where $R_{\theta JA(PCB)} \leq 120^\circ C/W$. De-rate at 12.5mA/°C above $T_A = 55^\circ C$ in this case.

† Recommended solder pad layout dimensions for this device, as detailed within this datasheet for the D-5B device.

Semelab plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing an order.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise stated)

| Symbols | Parameters | Test Conditions | Min. | Typ. | Max. | Units |
|-------------|--------------------------|---|------|------|------|---------------|
| V_{BR} | Breakdown Voltage | $I_R = 50\mu\text{A}$ | 220 | | | V |
| | | $T_A = -55^\circ\text{C}$ | 200 | | | |
| $V_F^{(5)}$ | Forward Voltage | $I_F = 1.5\text{A}$ | 0.5 | | 1.0 | V |
| | | $T_A = -55^\circ\text{C}$ | 0.5 | | 1.2 | |
| V_F | Forward Voltage (Pulsed) | $I_F = 9.0\text{A}$; duty $\leq 2\%$, $t_p \leq 8.3\text{ms}$ | 0.6 | | 1.2 | V |
| | | $T_A = 125^\circ\text{C}$ | | | 1.2 | |
| | | $T_A = -55^\circ\text{C}$ | | | 1.5 | |
| I_R | Reverse Current | $V_R = 200\text{V}$ | | | 1.0 | μA |
| | | $T_A = 125^\circ\text{C}$ | | | 60 | |

DYNAMIC CHARACTERISTICS

| | | | | | | |
|----------|-----------------------|--|--|--|-----|---------------|
| t_{rr} | Reverse Recovery Time | $I_F = 0.5\text{A}$, $I_{RM} = 1.0\text{A}$ $I_{REC} = 0.25\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ (min) | | | 2.0 | μs |
|----------|-----------------------|--|--|--|-----|---------------|

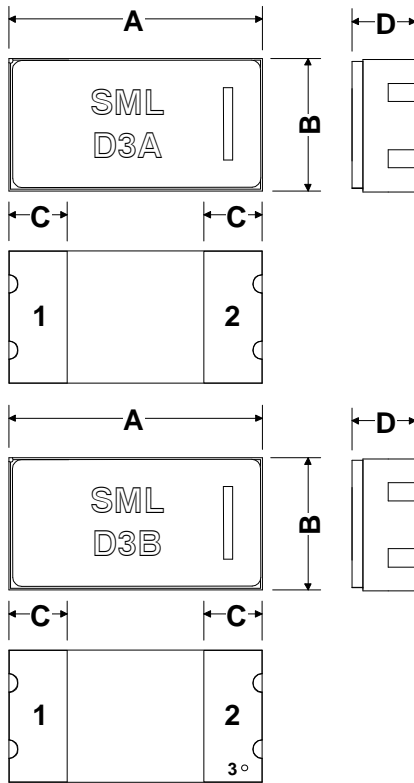
Notes:

(5) Pulse Width $\leq 300\mu\text{s}$, $\delta \leq 2\%$

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MECHANICAL DATA



DLCC3 Variant A (D3A)

| | | |
|-----------|------------|--------------|
| PAD 1 | ANODE | |
| PAD 2 | CATHODE | |
| | | |
| DIMENSION | mm | Inches |
| A | 7.00 ±0.10 | 0.275 ±0.004 |
| B | 3.75 ±0.10 | 0.143 ±0.004 |
| C | 1.60 ±0.10 | 0.063 ±0.004 |
| D | 1.76 ±0.10 | 0.069 ±0.004 |

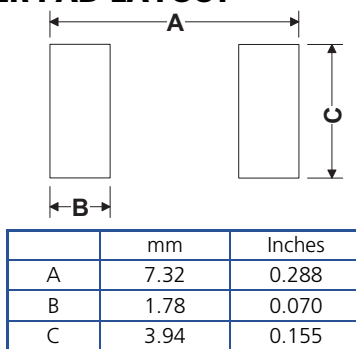
DLCC3 Variant B (D3B)

| | | |
|-----------|-------------------------|--------------|
| PAD 1 | ANODE | |
| PAD 2 | CATHODE | |
| PAD 3 | LID CONTACT TO CATHODE* | |
| | | |
| DIMENSION | mm | Inches |
| A | 7.00 ±0.10 | 0.275 ±0.004 |
| B | 3.75 ±0.10 | 0.143 ±0.004 |
| C | 1.60 ±0.10 | 0.063 ±0.004 |
| D | 1.76 ±0.10 | 0.069 ±0.004 |

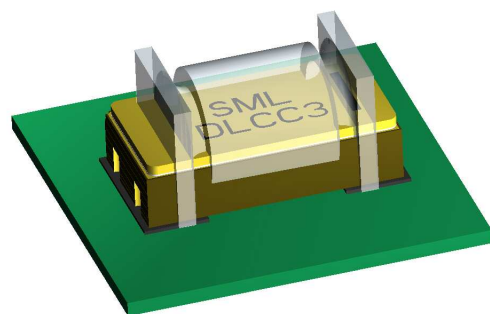
* The additional contact provides a connection to the lid in the application. Connecting the metal lid to a known electrical potential stops deep dielectric discharge in space applications; see the Space Weather link www.semelab.co.uk/dlcc3.html on the Semelab web site. Package variant to be specified at order.

† The DLCC3 package design takes full advantage of the proven high reliability pedigree of the HTCC surface mount packaging technology, which is easily integrated for automated assembly. Semelab has taken the existing standards for ceramic surface mount package manufacture and added additional design features to enhance thermal performance, to present a competitive alternative for high reliability applications.

SOLDER PAD LAYOUT



Soldering temperature should be 260°C for a maximum of 10 seconds.



The physical dimensions for the DLCC3 ceramic package are designed to be different from the published dimensions for the "D-5B" and "E-MELF" outlines. The DLCC3 design fully utilises the recommended solder footprint for the "D-5B" / "E-MELF" Package, and as such presents a drop in replacement for existing board designs.

PACKAGE MASS

Gold Plated Solder Pad Finish = 150mg

ULTRAFAST RECOVERY POWER RECTIFIER DIODE

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SCREENING OPTIONS

Space Level (JQRS/ESA) and High Reliability options are available in accordance with the [High Reliability and Screening Options Handbook](#) available for download from the from the TT electronics Semelab web site.

ESA Quality Level Products are based on the testing procedures specified in the generic ESCC 5000 and in the corresponding part detail specifications.

Semelab's QR216 and QR217 processing specifications (JQRS), in conjunction with the companies ISO 9001:2000 approval present a viable alternative to the American MIL-PRF-19500 space level processing.

QR217 (Space Level Quality Conformance) is based on the quality conformance inspection requirements of MIL-PRF-19500 groups A (table V), B (table VIa), C (table VII) and also ESA / ESCC 5000 (chart F4) lot validation tests.

QR216 (Space Level Screening) is based on the screening requirements of MIL-PRF-19500 (table IV) and also ESA /ESCC 5000 (chart F3).

JQRS parts are processed to the device data sheet and screened to QR216 with conformance testing to Q217 groups A and B in accordance with MIL-STD-750 methods and procedures.

Additional conformance options are available, for example Pre-Cap Visual Inspection, Buy-Off Visit or Data Packs. These are chargeable and must be specified at the order stage (See Ordering Information). Minimum order quantities may apply.

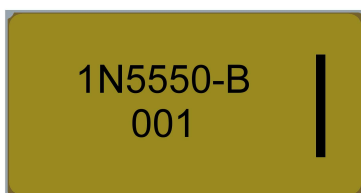
Alternative or additional customer specific conformance or screening requirements would be considered. Contact Semelab sales with enquires.

MARKING DETAILS

Parts can be laser marked with approximately 7 characters on two lines and always includes cathode identification. Typical marking would include part or specification number, week of seal or serial number subject to available space and legibility.

Customer specific marking requirements can be arranged at the time of order.

Example Marking:



ORDERING INFORMATION

Part numbers are built up from Type, Package Variant, and screening level. The part numbers are extended to include the additional options as shown below.

Type – See Electrical Stability Characteristics Table
Package Variant – See Mechanical Data
Screening Level – See Screening Options (ESA / JQRS)

Additional Options:

| | |
|--|-------------------|
| Customer Pre-Cap Visual Inspection | .CVP |
| Customer Buy-Off visit | .CVB |
| Data Pack | .DA |
| Solderability Samples | .SS |
| Scanning Electron Microscopy | .SEM |
| Radiography (X-ray) | .XRAY |
| Total Dose Radiation Test | .RAD |
| MIL-PRF-19500 (QR217) | |
| Group B charge | .GRPB |
| Group B destructive mechanical samples | .GBDM (12 pieces) |
| Group C charge | .GRPC |
| Group C destructive electrical samples | .GCDE (12 pieces) |
| Group C destructive mechanical samples | .GCDM (6 pieces) |
| ESA/ESCC | |
| Lot Validation Testing (subgroup 1) charge | .LVT1 |
| LVT1 destructive samples (environmental) | .L1DE (15 pieces) |
| LVT1 destructive samples (mechanical) | .L1DM (15 pieces) |
| Lot Validation Testing (subgroup 2) charge | .LVT2 |
| LVT2 endurance samples (electrical) | .L2D (15 pieces) |
| Lot Validation Testing (subgroup 3) charge | .LVT3 |
| LVT3 destructive samples (mechanical) | .L3D (5 pieces) |

Additional Option Notes:

- 1) All 'Additional Options' are chargeable and must be specified at order stage.
- 2) When Group B,C or LVT is required, additional electrical and mechanical destructive samples must be ordered
- 3) All destructive samples are marked the same as other production parts unless otherwise requested.

Example ordering information:

The following example is for the 1N5550D3 part with package variant B, JQRS screening, additional Group C conformance testing and a Data pack.

Part Numbers:

- 1N5550D3B-JQRS (Include quantity for flight parts)
- 1N5550D3B-JQRS.GRPC (chargeable conformance option)
- 1N5550D3B-JQRS.GCDE (charge for destructive parts)
- 1N5550D3B-JQRS.GCDM (charge for destructive parts)
- 1N5550D3B-JQRS.DA (charge for Data pack)

Customers with any specific requirements (e.g. marking or screening) may be supplied with a similar alternative part number (there is maximum 20 character limit to part numbers). Contact Semelab sales with enquiries